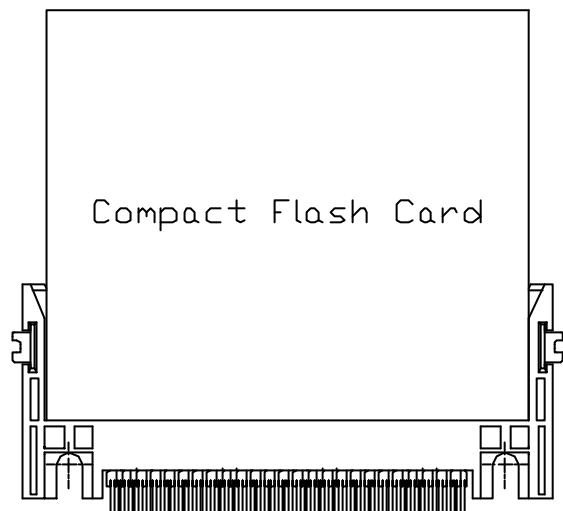
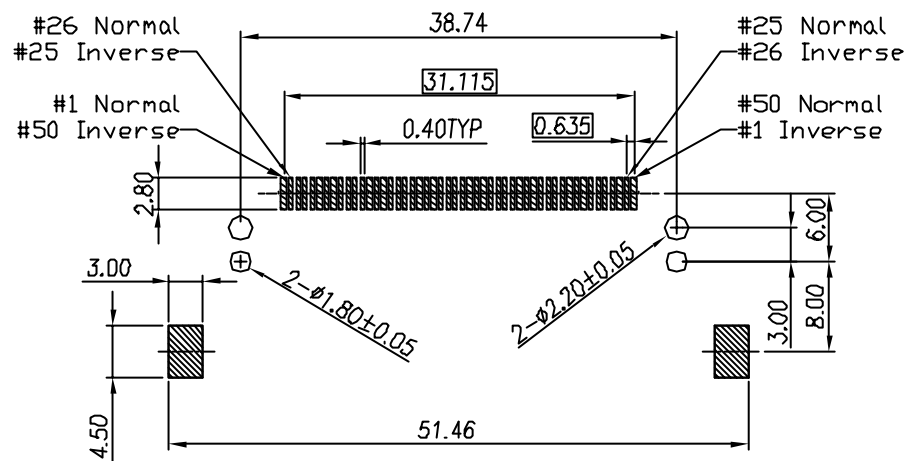
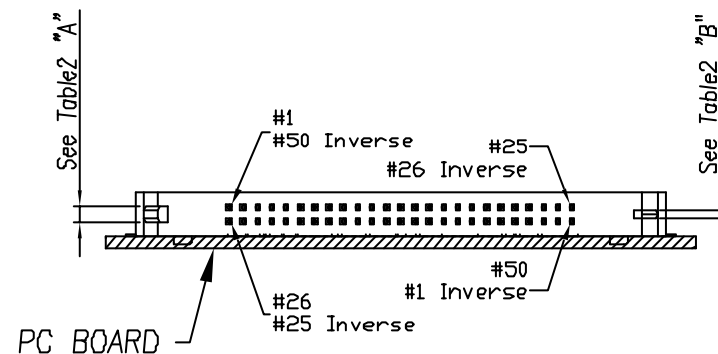


煜倫股份有限公司



CARD INSERTION



RECOMMENDED P.C.B. LAYOUT

MATERIAL

HOUSING: HIGH TEMPERATURE THERMOPLASTIC.

CONTACT: COPPER ALLOY.

PCB: BRASS.

PLATING

CONTACT: UNDERPLATED: 50 μ MIN NI.

CONTACT AREA: SELECTED GOLD OVER NI PLATED.

SOLDER TAIL: 100 μ MIN Tin OVER NI PLATED.

PCB: 100 μ MIN Tin OVER 50 μ MIN NI PLATED.

MORETHANALL
CONNECTORS
ASSEMBLIES

PART NO. CFC-PW38BE00xL12-50

DWG NO. CFC-PW38BE00xL12-50

FILE NO.

UNIT / mm

SCALE 1:1

CHECKED BY CY

DRAWING BY

PROJECTION

TOLERANCES ARE

.X $\pm$ 0.2

.XX $\pm$

.XXX $\pm$

AWG

DESCRIPTION:

AREA

REVISIONS

HK

DATE

煜倫股份有限公司